

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
DONG HA SHIN	09/20/2019
JE MAN LEE	09/20/2019
SEUNG-CHUL LEE	09/20/2019
KANG HO KIM	09/20/2019
RECEIVING PARTY DATA	
Name:	SANGMYUNG UNIVERSITY INDUSTRY-ACADEMY COOPERATION FOUNDATION
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Name:	ELECTRONICS AND TELECOMMUNICATIONS RESEARCH INSTITUTE
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16659761
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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NAME OF SUBMITTER:	WILLIAM J. KNOTTS, JR.

PATENT

SIGNATURE:	/wjk53145/
DATE SIGNED:	10/23/2019
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 3 source=2019-10-24_DeclarationandAssignment_executed_#page1.tif source=2019-10-24_DeclarationandAssignment_executed_#page2.tif source=2019-10-24_DeclarationandAssignment_executed_#page3.tif	

DECLARATION (37CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

As the below named inventor, I hereby declare that:

This declaration is directed to : [X] The attached application, or [] United States application number _____ or PCT application number _____ filed on _____ and was amended on (if applicable) _____.

Title: METHOD AND APPARATUS FOR TRANSFORMATION OF MPI PROGRAMS FOR MEMORY CENTRIC COMPUTERS

The above-identified application was made or authorized to be made by me.

I believe that I am the original, first inventor or an original, first and joint inventor of a claimed Invention in the application and for which a patent is sought.

I hereby state that I have reviewed and understand the contents of the above-identified application, including the specification and claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulation, Section 1.56.

Whereas, I/we, the below-identified inventor(s), have invented certain new and useful improvements in the Invention identified above and described in the above-identified application (referred to herein as the "Invention");

And, whereas I/we desire to assign the entire worldwide right, title and interest in and to the invention and to any and all patent applications and patents directed thereto to the Assignee identified below:

Assignee Name (if applicable): SANGMYUNG UNIVERSITY INDUSTRY-ACADEMY COOPERATION FOUNDATION

Assignee Address (if applicable): 20, Hongjimun 2-gil Jongno-gu, Seoul 03016 REPUBLIC OF KOREA

Assignee Name (if applicable): ELECTRONICS AND TELECOMMUNICATIONS RESEARCH INSTITUTE

Assignee Address (if applicable): 218, Gajeong-ro Yuseong-gu, Daejeon 34129 REPUBLIC OF KOREA

Now, this indenture witnesseth, that for good and valuable consideration, the receipt whereof is hereby acknowledged;

I/we hereby assign, sell and transfer my/our above-identified rights, title and interest in said Invention, said application identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted or have granted for said Invention, and in and to any and all reissues and reexaminations thereof, and in and to any and all priority rights, Convention rights, and other benefits accruing or to accrue to me/us with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, unto said Assignee;

And I/we hereby authorize and request the Director of the United States Patent and Trademark Office to issue any United States Letters Patent which may issue for said Invention to said Assignee, as assignee of the whole right, title and interest thereto;

And I/we further agree to sign and execute all necessary and lawful future documents, including applications for foreign patents, for filing divisions, continuations and continuations-in-part of said application for patent, and/or for obtaining any reissue or reissues of any Letters Patent which may be granted for my/our aforesaid Invention, as the Assignee or its Designee(s) may from time to time require and prepare at its own expense.

I/we hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Legal Name of Inventor (Assignor if applicable), Dong Ha SHIN:

Signature: Dongha Shin Date: September 20, 2019

Country of Citizenship: KR

Witnessed By (if applicable): Chanhee Kim Date: September 24, 2019

Signature: Chanhee Kim City: Seoul State: Seoul

Witnessed By (if applicable): Date:

Signature: City: State:

Legal Name of Inventor (Assignor if applicable), **Je Man LEE:**

Signature: *Je Man Lee* Date: September 20, 2019

Country of Citizenship: KR

Witnessed By (if applicable): Chanhee Kim Date: September 24, 2019

Signature: Chanhee Kim City: Seoul State: Seoul

Witnessed By (if applicable): _____ Date: _____

Signature: _____ City: _____ State: _____

Legal Name of Inventor (Assignor if applicable), **Seung-Chul LEE:**

Signature: *Seung-Chul Lee* Date: September 20, 2019

Country of Citizenship: KR

Witnessed By (if applicable): Chanhee Kim Date: September 24, 2019

Signature: Chanhee Kim City: Seoul State: Seoul

Witnessed By (if applicable): _____ Date: _____

Signature: _____ City: _____ State: _____

Legal Name of Inventor (Assignor if applicable), **Kang Ho KIM:**

Signature: *Kang Ho Kim* Date: September 20, 2019

Country of Citizenship: KR

Witnessed By (if applicable): Chanhee Kim Date: September 24, 2019

Signature: Chanhee Kim City: Seoul State: Seoul

Witnessed By (if applicable): _____ Date: _____

Signature: _____ City: _____ State: _____